

FMP20N60S1

FUJI POWER MOSFET

Super J-MOS series

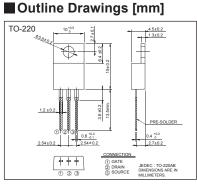
N-Channel enhancement mode power MOSFET

Features

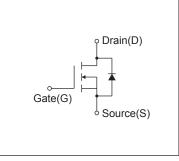
Low on-state resistance Low switching loss easy to use (more controllabe switching dV/dt by R_g)

Applications

UPS Server Telecom Power conditioner system Power supply



Equivalent circuit schematic



Maximum Ratings and Characteristics

● Absolute Maximum Ratings at T₀=25°C (unless otherwise specified)

Description	Symbol	Characteristics	Unit	Remarks	
Drain Source Voltage	V _{DS}	600	V		
Drain-Source Voltage	VDSX	600	V	V _{GS} =-30V	
Continuous Drain Current	lo	±20	А	Tc=25°C Note*1	
		±12.6	А	Tc=100°C Note*1	
Pulsed Drain Current	IDP	±60	А		
Gate-Source Voltage	Vgs	±30	V		
Repetitive and Non-Repetitive	LAR.	6.6	А	Note *2	
Maximum Avalanche Current	IAR	0.0		11010 2	
Non-Repetitive	Eas	472.2	mJ	Note *3	
Maximum Avalanche Energy	Eno				
Maximum Drain-Source dV/dt	dV _{DS} /dt	50	kV/µs	V _{DS} ≤ 600V	
Peak Diode Recovery dV/dt	dV/dt	15	kV/µs	Note *4	
Peak Diode Recovery -di/dt	-di/dt	100	A/µs	Note *5	
Maximum Power Discinction	PD	2.02	W	Ta=25°C	
Maximum Power Dissipation		150	VV	Tc=25°C	
Operating and Storage Temperature range	Tch	150	°C		
Operating and Storage Temperature range	T _{stg}	-55 to +150	°C		

Note *1 : Limited by maximum channel temperature.

Note *1 : Limited by maximum channel temperature. Note *2 : T_{ch}≤150°C, See Fig.1 and Fig.2 Note *3 : Starting T_{ch}=25°C, I_As=2A, L=216mH, V_{DD}=60V, R_G=50Ω, See Fig.1 and Fig.2 EAS limited by maximum channel temperature and avalanche current. Note *4 : I_F≤-I_D, -di/dt=100A/μs, V_{DD}≤400V, T_{ch}≤150°C. Note *5 : I_F≤-I_D, dV/dt=15kV/μs, V_{DD}≤400V, T_{ch}≤150°C.

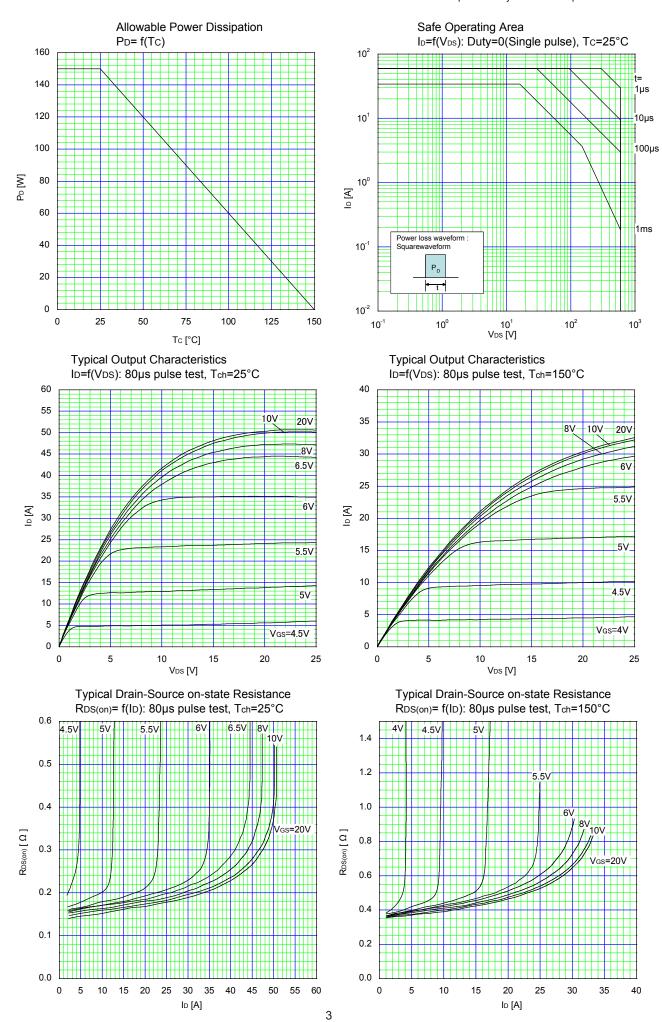
● Electrical Characteristics at T₀=25°C (unless otherwise specified) Static Ratings

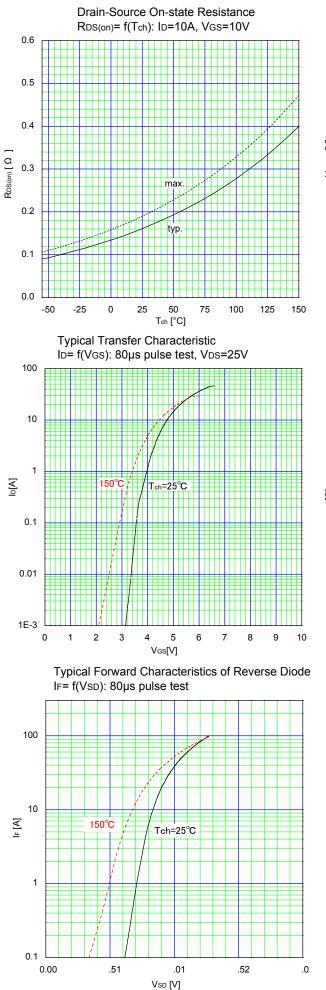
Description	Symbol	Conditions		min.	typ.	max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	I _D =250μA V _{GS} =0V		600	-	-	V
Gate Threshold Voltage	V _{GS(th)}	ID=250µA VDS=VGS		2.5	3	3.5	V
Zero Gate Voltage Drain Current	Ipss	V _{DS} =600V V _{GS} =0V	T _{ch} =25°C	-	-	25	μA
Zero Gate voltage Drain Current	IDSS	V _{DS} =480V V _{GS} =0V	T _{ch} =125°C	-	-	250	
Gate-Source Leakage Current	lgss	V _{GS} =±30V V _{DS} =0V		-	10	100	nA
Drain-Source On-State Resistance	R _{DS(on)}	I _D =10A V _{GS} =10V			0.161	0.19	Ω
Gate resistance	Rg	f=1MHz, open drain		-	3.7	-	Ω
Forward Transconductance	g _{fs}	I _D =10A V _{DS} =25V			17.5	-	S
Input Capacitance	Ciss	V _{DS} =10V		-	1470	-	pF
Output Capacitance	Coss	V _{GS} =0V			3120	-	
Reverse Transfer Capacitance	Crss	f=1MHz			280	-	
Effective output capacitance, energy related (Note *6)	C _{o(er)}				90	-	
Effective output capacitance, time related (Note *7)	C _{o(tr)}	V _{GS} =0V V _{DS} =0480V ID=constant		-	305	-	
Turn-On Time	t _{d(on)}		-	22	-	ns	
Turn-On Thine	tr	− V _{DD} =400V, V _{GS} =10V − J _D =10A, R _G =27Ω	-	40	-		
Turn-Off Time	td(off)	See Fig.3 and Fig.4	-	162	-		
	tr	See Fig.5 and Fig.4	-	22	-		
Total Gate Charge	QG				48	-	
Gate-Source Charge	QGS	V⊳D=480V, ID=20A VGs=10V - See Fig.5		-	12.5	-	nC
Gate-Drain Charge	QGD			-	15	-	
Drain-Source crossover Charge	Qsw			-	8	-	
Avalanche Capability	lav	L=6.02mH, T _{ch} =25°C See Fig.1 and Fig.2			-	-	А
Diode Forward On-Voltage	V _{SD}	IF=20A, VGS=0V Tch=25°C		-	0.9	1.35	V
Reverse Recovery Time	trr	I _F =20A, V _{GS} =0V V _{DD} =400V -di/dt=100A/μs T _{ch} =25°C See Fig.6			370	-	ns
Reverse Recovery Charge	Qrr			-	6.2	-	μC
Peak Reverse Recovery Current	Irp			-	32	-	A

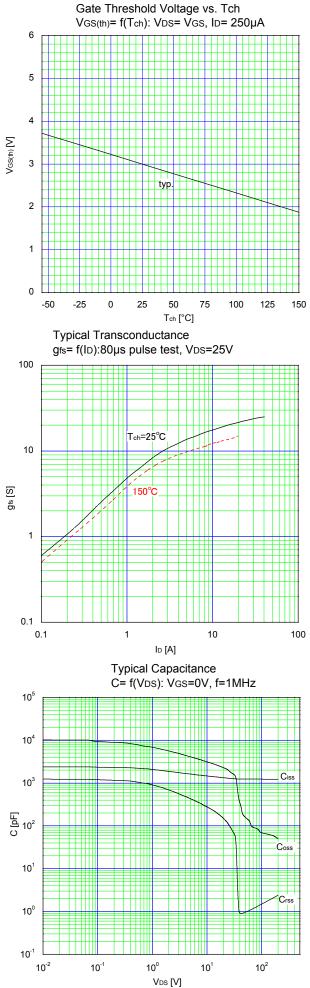
Note *6 : $C_{o(er)}$ is a fixed capacitance that gives the same stored energy as C_{oss} while V_{Ds} is rising from 0 to 80% BV_{Dss}. Note *7 : $C_{o(tr)}$ is a fixed capacitance that gives the same charging times as C_{oss} while V_{Ds} is rising from 0 to 80% BV_{Dss}.

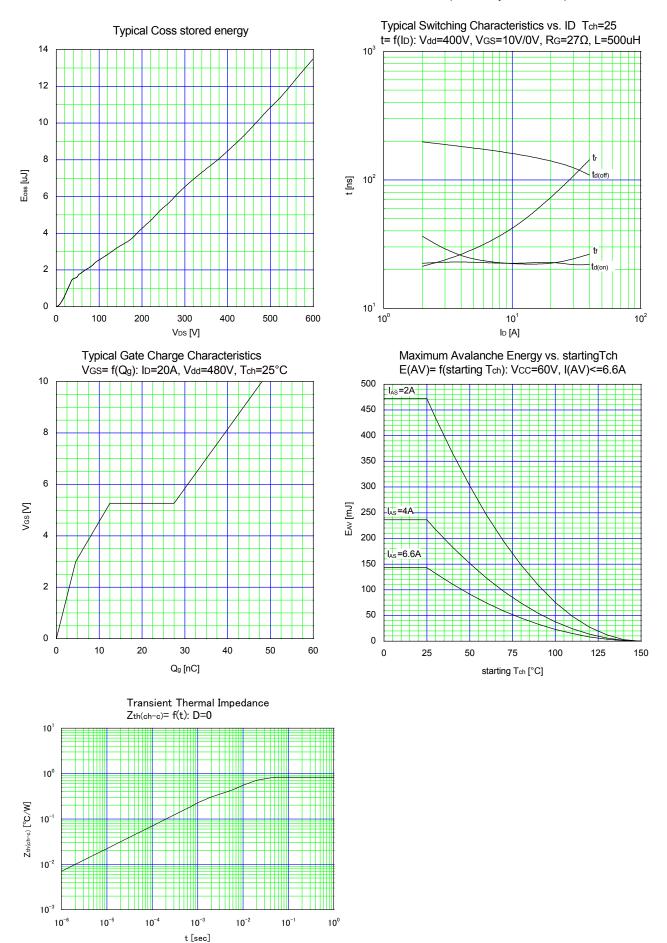
Thermal Characteristics

Description	Symbol	min.	typ.	max.	Unit
Channel to Case	Rth(ch-c)			0.83	°C/W
Channel to Ambient	Rth(ch-a)			62	°C/W

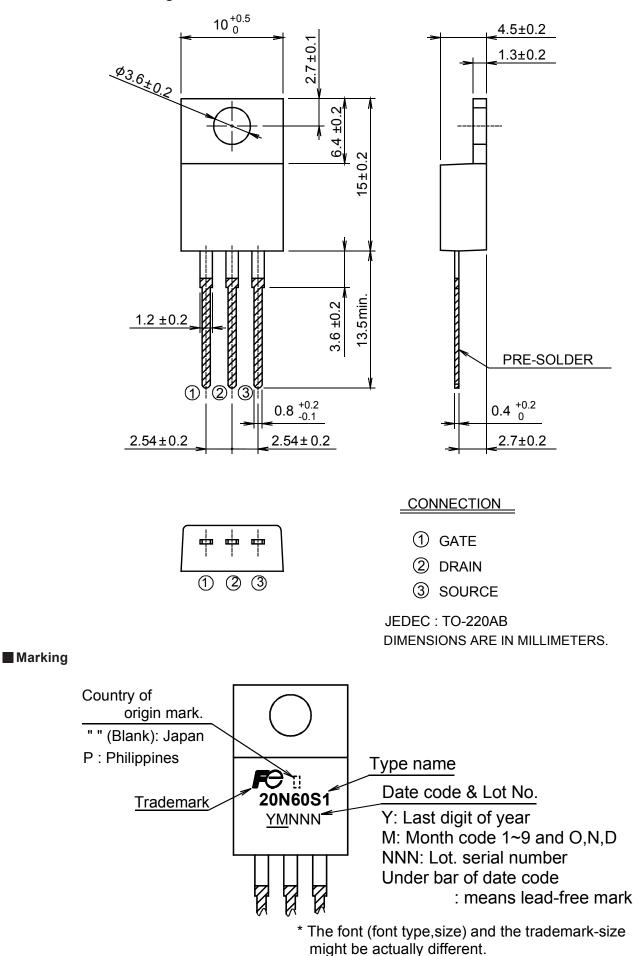








Outview: TO-220 Package



WARNING

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